

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicants: Hoffman, Paul; Mathews, Doug
Assignee: Amkor Technology, Inc.
Title: Shielded Semiconductor Package With Single Sided Substrate And Method For Making The Same
Serial No.: 09/848,932 Filing Date: May 4, 2001
Examiner: Cruz, Lourdes C.) Group Art Unit: 2827
Docket No.: M-9954 US

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RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

Applicants respond to the Office Action dated June 21, 2002 as follows. Applicants elect Group I, i.e., claims 11-21. Applicants are canceling claims 1-10 and are adding new claims 22-31.

IN THE CLAIMS

Please cancel claims 1-10 and add new claims 22-31. Claim 20 has been amended to correct a minor typographical error. The following is a clean version of the entire set of pending claims. In accordance with 37 C.F.R. §1.121(c)(1)(ii), Attachment A provides marked up version of claim 20 containing the newly introduced changes.

Claims 1-10 are cancelled.

11. A semiconductor chip package comprising:
a substrate;
a metallization layer formed on one side of the substrate;

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